

# DXP-C5LSG

This equipment cooperates with the multi-wire cutting machine to adjust the bonding of the X and Y axes of the crystal rod respectively.

- The Equipment is a Double-work bench.
- One side of the worktable is used in conjunction with the fixture to adjust the Y-axis of the crystal ingot.
- The worktable on the other side is used in conjunction with the cutting machine material plate to perform directional bonding of the crystal rod in the X-axis.
- Manual measurement and manual peak determination.
- Requires surface grinder for use.

Item	Specifications
Crystal Diameter	Ingot 2, 4, 6 inches
Crystal length	Ingot length within 300mm
Measurement angle	0~35°
Accuracy	±30" or ±15"



## Structure A

1. Traditional mechanical structure.
2. It is recommended that the worktable load is within 25kg (ingot + plate).
3. Manual calibration, which requires the device to be calibrated each time it is switched on.
4. Suitable range of material plate length: 420mm or less.



## Structure B

1. Upgraded to a photoelectric sensor structure to improve the spindle rotation accuracy, reduce mechanical errors, and make the structure more stable.
2. It is recommended that the load of the worktable should be within 50kg (crystal ingot + material plate).
3. Calibration-free machine function.
4. Suitable range of material plate length: 420mm ~ 600mm.